

74HC594; 74HCT594

8-bit shift register with output register

Rev. 03 — 20 December 2006

Product data sheet

1. General description

The 74HC594; 74HCT594 is a high-speed Si-gate CMOS device and is pin compatible with Low-Power Schottky TTL (LSTTL).

The 74HC594; 74HCT594 is an 8-bit, non-inverting, serial-in, parallel-out shift register that feeds an 8-bit D-type storage register. Separate clocks (SHCP and STCP) and direct overriding clears (SHR and STR) are provided on both the shift and storage registers. A serial output (Q7S) is provided for cascading purposes.

Both the shift and storage register clocks are positive-edge triggered. If the user wishes to connect both clocks together, the shift register will always be one count pulse ahead of the storage register.

2. Features

- Synchronous serial input and output
- Complies with JEDEC standard No.7A
- 8-bit parallel output
- Shift and storage registers have independent direct clear and clocks
- Independent clocks for shift and storage registers
- 100 MHz (typical)
- Multiple package options
- Specified from $-40\text{ }^{\circ}\text{C}$ to $+85\text{ }^{\circ}\text{C}$ and from $-40\text{ }^{\circ}\text{C}$ to $+125\text{ }^{\circ}\text{C}$

3. Applications

- Serial-to parallel data conversion
- Remote control holding register

4. Ordering information

Table 1. Ordering information

Type number	Package			Version
	Temperature range	Name	Description	
74HC594D	−40 °C to +125 °C	SO16	plastic small outline package; 16 leads; body width 3.9 mm	SOT109-1
74HC594DB	−40 °C to +125 °C	SSOP16	plastic shrink small outline package; 16 leads; body width 5.3 mm	SOT338-1
74HC594N	−40 °C to +125 °C	DIP16	plastic dual in-line package; 16 leads (300 mil)	SOT38-4
74HCT594D	−40 °C to +125 °C	SO16	plastic small outline package; 16 leads; body width 3.9 mm	SOT109-1
74HCT594DB	−40 °C to +125 °C	SSOP16	plastic shrink small outline package; 16 leads; body width 5.3 mm	SOT338-1
74HCT594N	−40 °C to +125 °C	DIP16	plastic dual in-line package; 16 leads (300 mil)	SOT38-4

5. Functional diagram

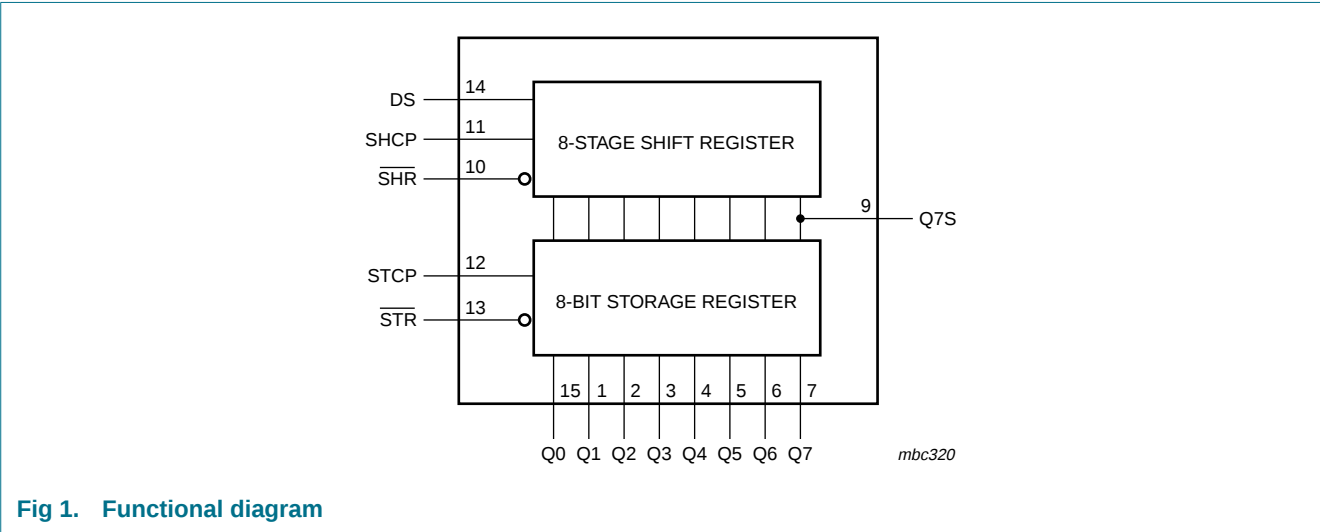


Fig 1. Functional diagram

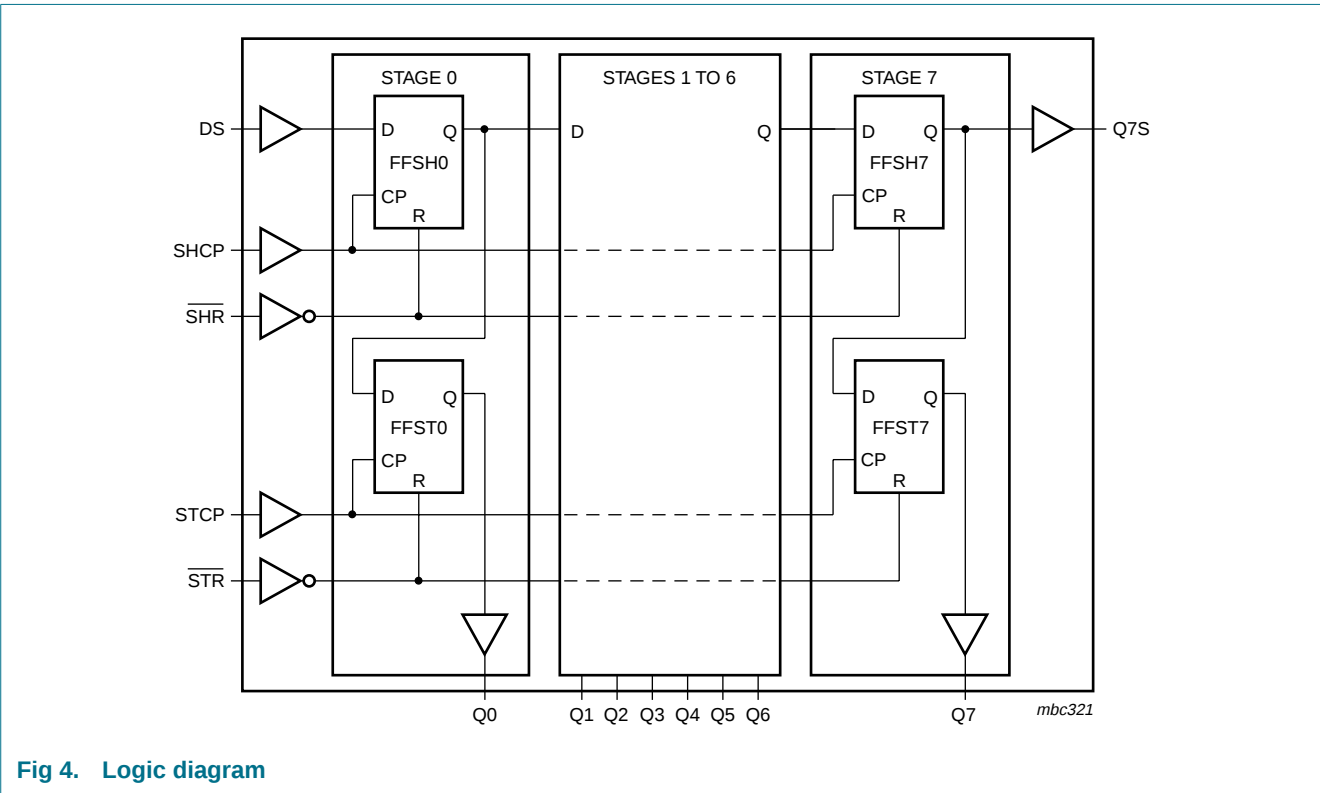
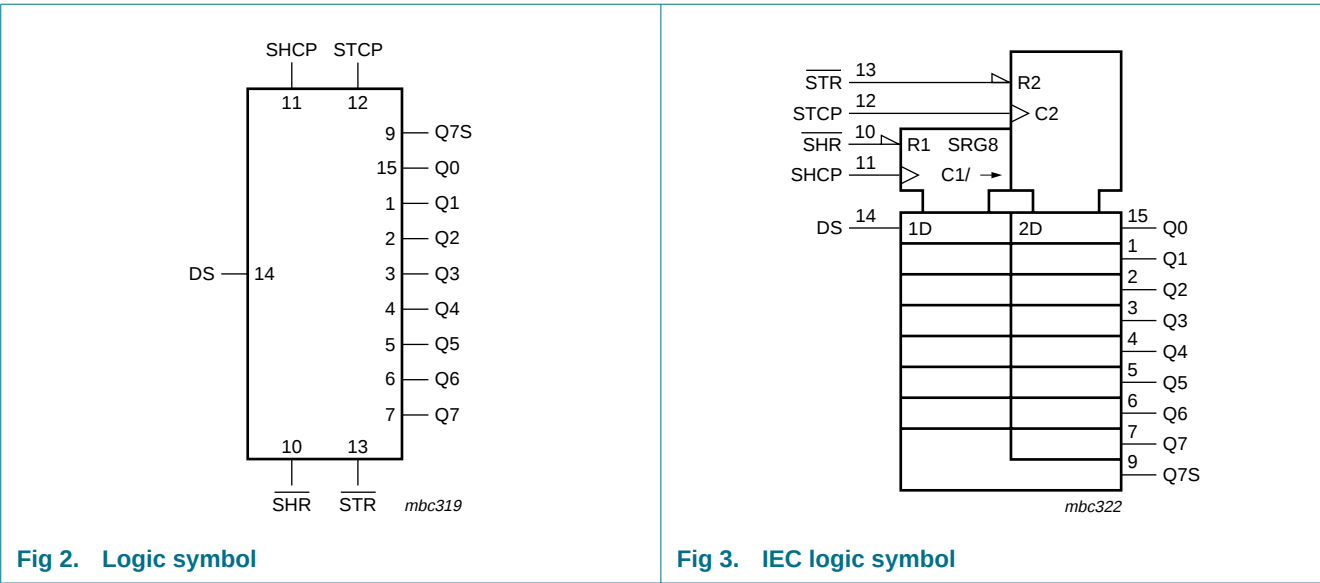
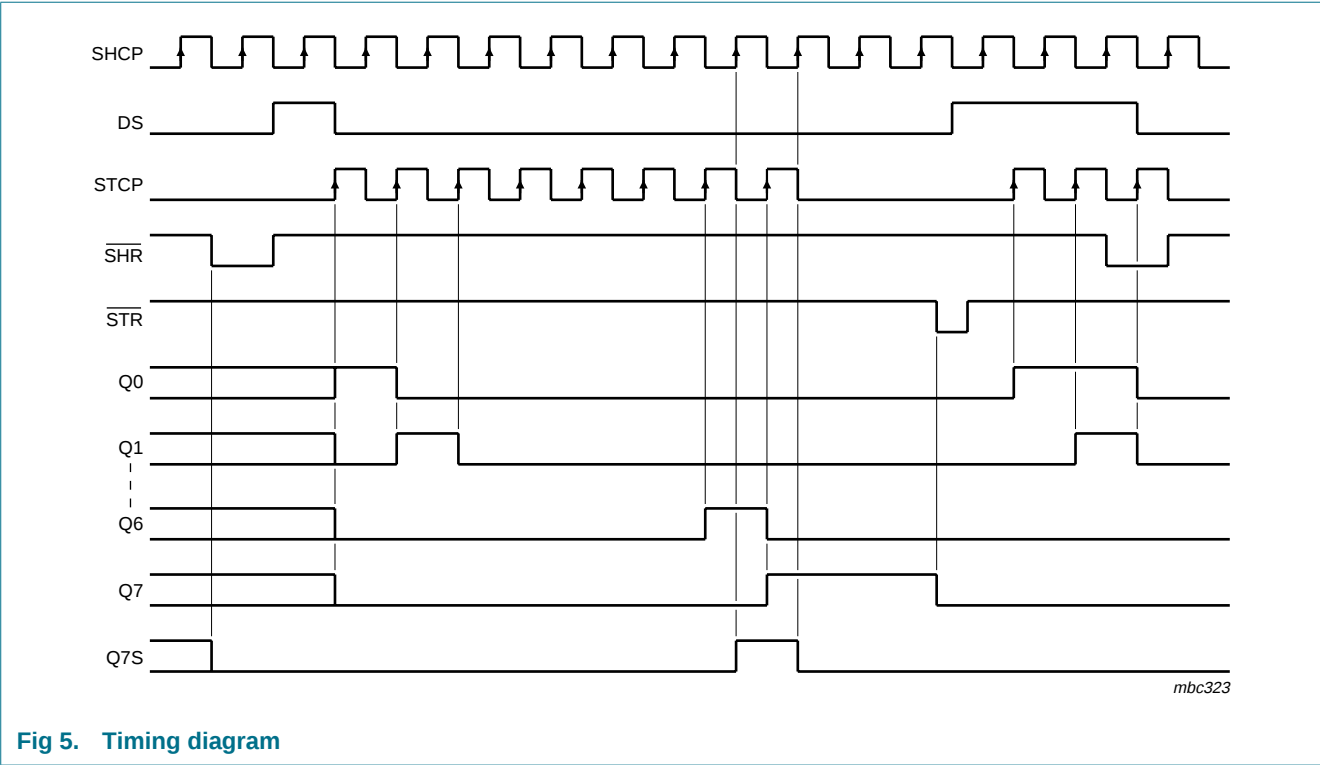
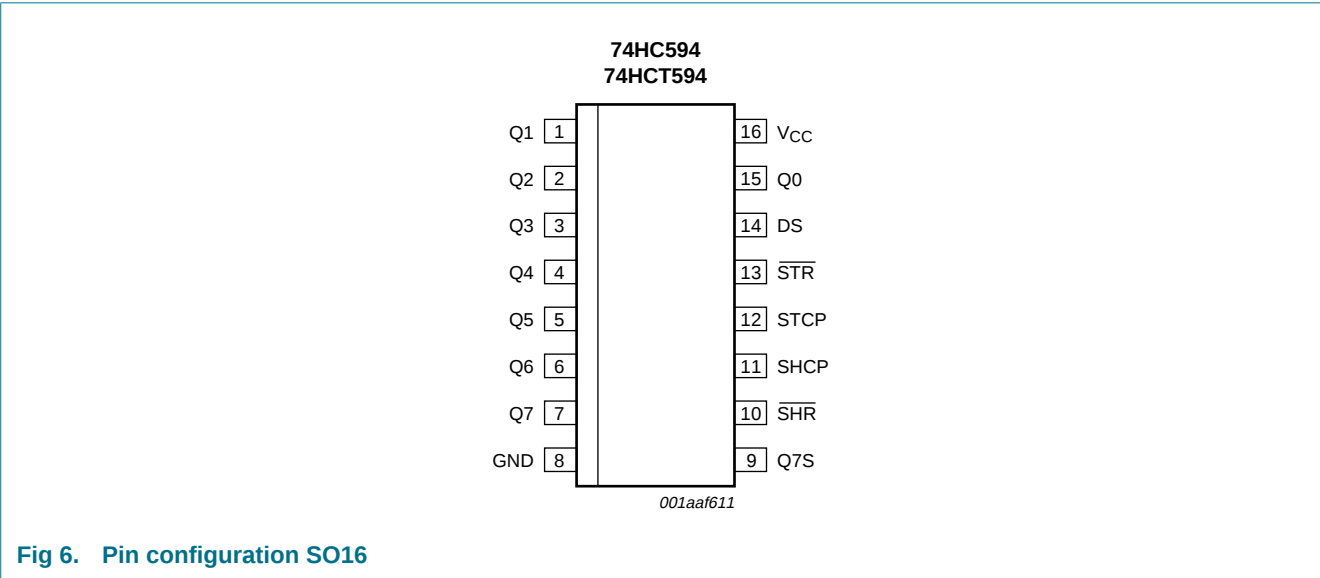


Fig 4. Logic diagram



6. Pinning information

6.1 Pinning



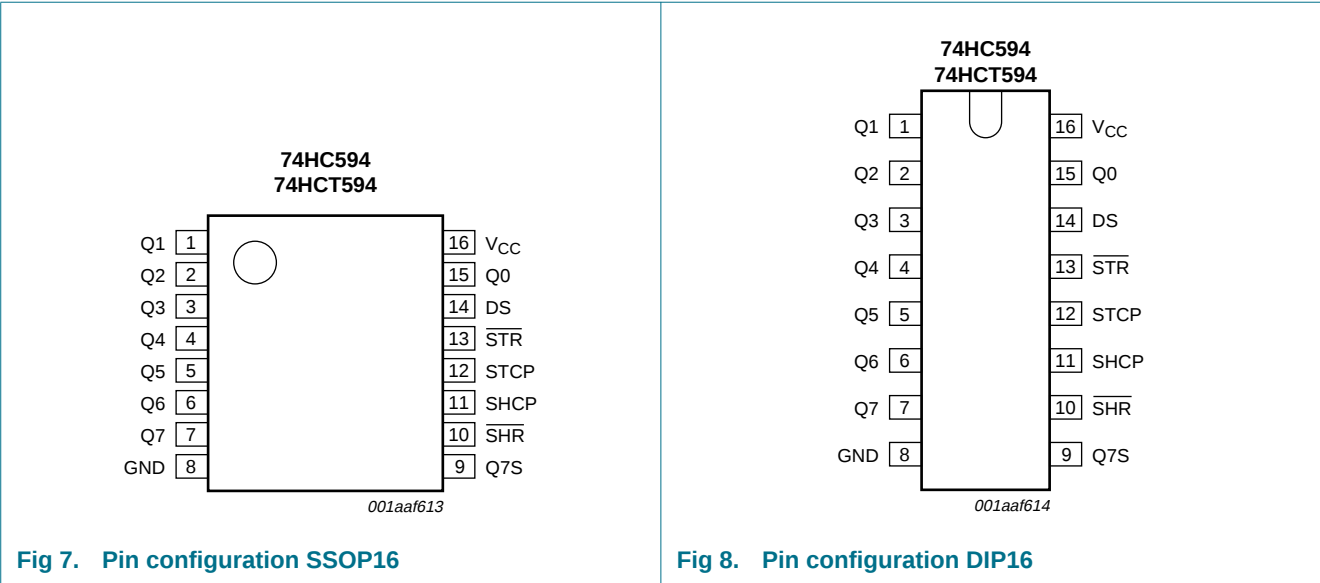


Fig 7. Pin configuration SSOP16

Fig 8. Pin configuration DIP16

6.2 Pin description

Table 2. Pin description

Symbol	Pin	Description
Q1	1	parallel data output 1
Q2	2	parallel data output 2
Q3	3	parallel data output 3
Q4	4	parallel data output 4
Q5	5	parallel data output 5
Q6	6	parallel data output 6
Q7	7	parallel data output 7
GND	8	ground (0 V)
Q7S	9	serial data output
SHR	10	shift register reset (active LOW)
SHCP	11	shift register clock input
STCP	12	storage register clock input
STR	13	storage register reset (active LOW)
DS	14	serial data input
Q0	15	parallel data output 0
VCC	16	supply voltage

7. Functional description

Table 3. Function table^[1]

Function	Input				
	SHR	STR	SHCP	STCP	DS
Clear shift register	L	X	X	X	X
Clear storage register	X	L	X	X	X
Load DS into shift register stage 0, advance previous stage data to the next stage	H	X	↑	X	H or L
Transfer shift register data to storage register and outputs Qn	X	H	X	↑	X
Shift register one count pulse ahead of storage register	H	H	↑	↑	X

- [1] H = HIGH voltage level;
 L = LOW voltage level;
 ↑ = LOW-to-HIGH transition;
 X = don't care.

8. Limiting values

Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134). Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	Min	Max	Unit
V_{CC}	supply voltage		-0.5	+7.0	V
I_{IK}	input clamping current	$V_I < -0.5\text{ V}$ or $V_I > V_{CC} + 0.5\text{ V}$	^[1] -	±20	mA
I_{OK}	output clamping current	$V_O < -0.5\text{ V}$ or $V_O > V_{CC} + 0.5\text{ V}$	^[1] -	±20	mA
I_O	output current	$V_O = -0.5\text{ V}$ to $V_{CC} + 0.5\text{ V}$			
		Serial data output Q7S	-	±25	mA
		Parallel data output	-	±35	mA
I_{CC}	supply current	Serial data output Q7S	-	50	mA
		Parallel data output	-	70	mA
I_{GND}	ground current	Serial data output Q7S	-	-50	mA
		Parallel data output	-	-70	mA
T_{stg}	storage temperature		-65	+150	°C
P_{tot}	total power dissipation	$T_{amb} = -40\text{ °C}$ to $+125\text{ °C}$	^[2] -	500	mW

- [1] The input and output voltage ratings may be exceeded if the input and output current ratings are observed.
 [2] For DIP16 packages: above 70 °C the value of P_{tot} derates linearly with 12 mW/K.
 For SO16 packages: above 70 °C the value of P_{tot} derates linearly with 8 mW/K.
 For SSOP16 packages: above 60 °C the value of P_{tot} derates linearly with 5.5 mW/K.

9. Recommended operating conditions

Table 5. Recommended operating conditions

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
Type 74HC594						
V _{CC}	supply voltage		2.0	5.0	6.0	V
V _I	input voltage		0	-	V _{CC}	V
V _O	output voltage		0	-	V _{CC}	V
T _{amb}	ambient temperature		−40	+25	+125	°C
t _r	rise time	V _{CC} = 2.0 V	-	-	1000	ns
		V _{CC} = 4.5 V	-	6.0	500	ns
		V _{CC} = 6.0 V	-	-	400	ns
t _f	fall time	V _{CC} = 2.0 V	-	-	1000	ns
		V _{CC} = 4.5 V	-	6.0	500	ns
		V _{CC} = 6.0 V	-	-	400	ns
Type 74HCT594						
V _{CC}	supply voltage		4.5	5.0	5.5	V
V _I	input voltage		0	-	V _{CC}	V
V _O	output voltage		0	-	V _{CC}	V
T _{amb}	ambient temperature		−40	+25	+125	°C
t _r	rise time	V _{CC} = 4.5 V	-	6.0	500	ns
t _f	fall time	V _{CC} = 4.5 V	-	6.0	500	ns

10. Static characteristics

Table 6. Static characteristics type 74HC594

At recommended operating conditions; voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$T_{amb} = 25\text{ °C}$						
V_{IH}	HIGH-level input voltage	$V_{CC} = 2.0\text{ V}$	1.5	1.2	-	V
		$V_{CC} = 4.5\text{ V}$	3.15	2.4	-	V
		$V_{CC} = 6.0\text{ V}$	4.2	3.2	-	V
V_{IL}	LOW-level input voltage	$V_{CC} = 2.0\text{ V}$	-	0.8	0.5	V
		$V_{CC} = 4.5\text{ V}$	-	2.1	1.35	V
		$V_{CC} = 6.0\text{ V}$	-	2.8	1.8	V
V_{OH}	HIGH-level output voltage	$V_I = V_{IH}$ or V_{IL}				
		Serial data output Q7S				
		$I_O = -4.0\text{ mA}; V_{CC} = 4.5\text{ V}$	3.98	4.32	-	V
		Parallel data outputs				
		$I_O = -6.0\text{ mA}; V_{CC} = 4.5\text{ V}$	3.98	4.32	-	V
		$I_O = -7.8\text{ mA}; V_{CC} = 6.0\text{ V}$	5.48	5.81	-	V

Table 6. Static characteristics type 74HC594 ...continued

At recommended operating conditions; voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V _{OL}	LOW-level output voltage	V _I = V _{IH} or V _{IL}				
		Serial data output Q7S				
		I _O = 4.0 mA; V _{CC} = 4.5 V	-	0.15	0.26	V
		I _O = 5.2 mA; V _{CC} = 6.0 V	-	0.16	0.26	V
		Parallel data outputs				
		I _O = 6.0 mA; V _{CC} = 4.5 V	-	0.15	0.26	V
	I _O = 7.8 mA; V _{CC} = 6.0 V	-	0.16	0.26	V	
I _I	input leakage current	V _I = V _{CC} or GND; V _{CC} = 6.0 V	-	-	±0.1	μA
I _{CC}	supply current	V _I = V _{CC} or GND; I _O = 0 A; V _{CC} = 6.0 V	-	-	8.0	μA
C _i	input capacitance		-	3.5	-	pF
T _{amb} = -40 °C to +85 °C						
V _{IH}	HIGH-level input voltage	V _{CC} = 2.0 V	1.5	-	-	V
		V _{CC} = 4.5 V	3.15	-	-	V
		V _{CC} = 6.0 V	4.2	-	-	V
V _{IL}	LOW-level input voltage	V _{CC} = 2.0 V	-	-	0.5	V
		V _{CC} = 4.5 V	-	-	1.35	V
		V _{CC} = 6.0 V	-	-	1.8	V
V _{OH}	HIGH-level output voltage	V _I = V _{IH} or V _{IL}				
		Serial data output Q7S				
		I _O = -4.0 mA; V _{CC} = 4.5 V	3.84	-	-	V
		I _O = -5.2 mA; V _{CC} = 6.0 V	5.34	-	-	V
		Parallel data outputs				
		I _O = -6.0 mA; V _{CC} = 4.5 V	3.84	-	-	V
	I _O = -7.8 mA; V _{CC} = 6.0 V	5.34	-	-	V	
V _{OL}	LOW-level output voltage	V _I = V _{IH} or V _{IL}				
		Serial data output Q7S				
		I _O = 4.0 mA; V _{CC} = 4.5 V	-	-	0.33	V
		I _O = 5.2 mA; V _{CC} = 6.0 V	-	-	0.33	V
		Parallel data outputs				
		I _O = 6.0 mA; V _{CC} = 4.5 V	-	-	0.33	V
	I _O = 7.8 mA; V _{CC} = 6.0 V	-	-	0.33	V	
I _I	input leakage current	V _I = V _{CC} or GND; V _{CC} = 6.0 V	-	-	±1.0	μA
I _{CC}	supply current	V _I = V _{CC} or GND; I _O = 0 A; V _{CC} = 6.0 V	-	-	80	μA
T _{amb} = -40 °C to +125 °C						
V _{IH}	HIGH-level input voltage	V _{CC} = 2.0 V	1.5	-	-	V
		V _{CC} = 4.5 V	3.15	-	-	V
		V _{CC} = 6.0 V	4.2	-	-	V

Table 6. Static characteristics type 74HC594 ...continued

At recommended operating conditions; voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V_{IL}	LOW-level input voltage	$V_{CC} = 2.0\text{ V}$	-	-	0.5	V
		$V_{CC} = 4.5\text{ V}$	-	-	1.35	V
		$V_{CC} = 6.0\text{ V}$	-	-	1.8	V
V_{OH}	HIGH-level output voltage	$V_I = V_{IH}$ or V_{IL}				
		Serial data output Q7S				
		$I_O = -4.0\text{ mA}$; $V_{CC} = 4.5\text{ V}$	3.7	-	-	V
		$I_O = -5.2\text{ mA}$; $V_{CC} = 6.0\text{ V}$	5.2	-	-	V
		Parallel data outputs				
		$I_O = -6.0\text{ mA}$; $V_{CC} = 4.5\text{ V}$	3.7	-	-	V
		$I_O = -7.8\text{ mA}$; $V_{CC} = 6.0\text{ V}$	5.2	-	-	V
V_{OL}	LOW-level output voltage	$V_I = V_{IH}$ or V_{IL}				
		Serial data output Q7S				
		$I_O = 4.0\text{ mA}$; $V_{CC} = 4.5\text{ V}$	-	-	0.4	V
		$I_O = 5.2\text{ mA}$; $V_{CC} = 6.0\text{ V}$	-	-	0.4	V
		Parallel data outputs				
		$I_O = 6.0\text{ mA}$; $V_{CC} = 4.5\text{ V}$	-	-	0.4	V
I_I	input leakage current	$V_I = V_{CC}$ or GND; $V_{CC} = 6.0\text{ V}$	-	-	± 1.0	μA
		$V_I = V_{CC}$ or GND; $I_O = 0\text{ A}$; $V_{CC} = 6.0\text{ V}$	-	-	160	μA

Table 7. Static characteristics type 74HCT594

At recommended operating conditions; voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
T_{amb} = 25 °C						
V _{IH}	HIGH-level input voltage	V _{CC} = 4.5 V to 5.5 V	2.0	1.6	-	V
V _{IL}	LOW-level input voltage	V _{CC} = 4.5 V to 5.5 V	-	1.2	0.8	V
V _{OH}	HIGH-level output voltage	V _I = V _{IH} or V _{IL}				
		Serial data output Q7S				
		I _O = -4.0 mA; V _{CC} = 4.5 V	3.98	4.32	-	V
		Parallel data outputs				
		I _O = -6.0 mA; V _{CC} = 4.5 V	3.98	4.32	-	V
V _{OL}	LOW-level output voltage	V _I = V _{IH} or V _{IL}				
		Serial data output Q7S				
		I _O = 4.0 mA; V _{CC} = 4.5 V	-	0.15	0.26	V
		Parallel data outputs				
		I _O = 6.0 mA; V _{CC} = 4.5 V	-	0.16	0.26	V
I _I	input leakage current	V _I = V _{CC} or GND; V _{CC} = 5.5 V	-	-	±0.1	μA
I _{CC}	supply current	V _I = V _{CC} or GND; I _O = 0 A; V _{CC} = 5.5 V	-	-	8.0	μA
ΔI _{CC}	additional supply current	per input pin; V _I = V _{CC} - 2.1 V and other inputs at V _{CC} or GND; I _O = 0 A; V _{CC} = 4.5 V to 5.5 V				
		pins $\overline{\text{SHR}}$, SHCP, STCP, $\overline{\text{STR}}$	-	150	540	μA
		pin DS	-	25	90	μA
C _i	input capacitance		-	3.5	-	pF
T_{amb} = -40 °C to +85 °C						
V _{IH}	HIGH-level input voltage	V _{CC} = 4.5 V to 5.5 V	2.0	-	-	V
V _{IL}	LOW-level input voltage	V _{CC} = 4.5 V to 5.5 V	-	-	0.8	V
V _{OH}	HIGH-level output voltage	V _I = V _{IH} or V _{IL}				
		Serial data output Q7S				
		I _O = -4.0 mA; V _{CC} = 4.5 V	3.84	-	-	V
		Parallel data outputs				
		I _O = -6.0 mA; V _{CC} = 4.5 V	3.84	-	-	V
V _{OL}	LOW-level output voltage	V _I = V _{IH} or V _{IL}				
		Serial data output				
		I _O = 4.0 mA; V _{CC} = 4.5 V	-	-	0.33	V
		Parallel data outputs				
		I _O = 6.0 mA; V _{CC} = 4.5 V	-	-	0.33	V
I _I	input leakage current	V _I = V _{CC} or GND; V _{CC} = 5.5 V	-	-	±1.0	μA
I _{CC}	supply current	V _I = V _{CC} or GND; I _O = 0 A; V _{CC} = 5.5 V	-	-	80	μA

Table 7. Static characteristics type 74HCT594 ...continued

At recommended operating conditions; voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
ΔI_{CC}	additional supply current	per input pin; $V_I = V_{CC} - 2.1$ V and other inputs at V_{CC} or GND; $I_O = 0$ A; $V_{CC} = 4.5$ V to 5.5 V				
		pins $\overline{SHR}$, SHCP, STCP, $\overline{STR}$	-	-	675	μ A
		pin DS	-	-	112.5	μ A
$T_{amb} = -40$ °C to $+125$ °C						
V_{IH}	HIGH-level input voltage	$V_{CC} = 4.5$ V to 5.5 V	2.0	-	-	V
V_{IL}	LOW-level input voltage	$V_{CC} = 4.5$ V to 5.5 V	-	-	0.8	V
V_{OH}	HIGH-level output voltage	$V_I = V_{IH}$ or V_{IL}				
		Serial data output Q7S				
		$I_O = -4.0$ mA; $V_{CC} = 4.5$ V	3.7	-	-	V
		Parallel data outputs				
		$I_O = -6.0$ mA; $V_{CC} = 4.5$ V	3.7	-	-	V
V_{OL}	LOW-level output voltage	$V_I = V_{IH}$ or V_{IL}				
		Serial data output Q7S				
		$I_O = 4.0$ mA; $V_{CC} = 4.5$ V	-	-	0.4	V
		Parallel data outputs				
		$I_O = 6.0$ mA; $V_{CC} = 4.5$ V	-	-	0.4	V
I_I	input leakage current	$V_I = V_{CC}$ or GND; $V_{CC} = 5.5$ V	-	-	± 1.0	μ A
I_{CC}	supply current	$V_I = V_{CC}$ or GND; $I_O = 0$ A; $V_{CC} = 5.5$ V	-	-	160	μ A
ΔI_{CC}	additional supply current	per input pin; $V_I = V_{CC} - 2.1$ V and other inputs at V_{CC} or GND; $I_O = 0$ A; $V_{CC} = 4.5$ V to 5.5 V				
		pins $\overline{SHR}$, SHCP, STCP, $\overline{STR}$	-	-	735	μ A
		pin DS	-	-	122.5	μ A

11. Dynamic characteristics

Table 8. Dynamic characteristics type 74HC594

$GND = 0\text{ V}$; $t_r = t_f = 6\text{ ns}$; $C_L = 50\text{ pF}$; see [Figure 15](#).

Symbol	Parameter	Conditions	25 °C			–40 °C to +85 °C		–40 °C to +125 °C		Unit
			Min	Typ	Max	Min	Max	Min	Max	
t_{pd}	propagation delay	SHCP to Q7S; see Figure 9 ^[1]								
		$V_{CC} = 2.0\text{ V}$	-	44	150	-	185	-	225	ns
		$V_{CC} = 4.5\text{ V}$	-	16	30	-	37	-	45	ns
		$V_{CC} = 5.0\text{ V}$; $C_L = 15\text{ pF}$	-	13	-	-	-	-	-	ns
		$V_{CC} = 6.0\text{ V}$	-	14	26	-	31	-	38	ns
		STCP to Qn; see Figure 10								
		$V_{CC} = 2.0\text{ V}$	-	44	150	-	185	-	225	ns
		$V_{CC} = 4.5\text{ V}$	-	16	30	-	37	-	45	ns
		$V_{CC} = 5.0\text{ V}$; $C_L = 15\text{ pF}$	-	13	-	-	-	-	-	ns
		$V_{CC} = 6.0\text{ V}$	-	14	26	-	31	-	38	ns
t_{PHL}	HIGH to LOW propagation delay	SHR to Q7S; see Figure 13								
		$V_{CC} = 2.0\text{ V}$	-	39	150	-	185	-	225	ns
		$V_{CC} = 4.5\text{ V}$	-	14	30	-	37	-	45	ns
		$V_{CC} = 5.0\text{ V}$; $C_L = 15\text{ pF}$	-	11	-	-	-	-	-	ns
		$V_{CC} = 6.0\text{ V}$	-	12	26	-	31	-	38	ns
		STR to Qn; see Figure 14								
		$V_{CC} = 2.0\text{ V}$	-	39	125	-	155	-	185	ns
		$V_{CC} = 4.5\text{ V}$	-	14	25	-	31	-	37	ns
		$V_{CC} = 5.0\text{ V}$; $C_L = 15\text{ pF}$	-	11	-	-	-	-	-	ns
		$V_{CC} = 6.0\text{ V}$	-	12	21	-	26	-	31	ns
t_{THL}	HIGH to LOW output transition time	see Figure 9								
		Serial data output Q7S								
		$V_{CC} = 2.0\text{ V}$	-	19	75	-	95	-	110	ns
		$V_{CC} = 4.5\text{ V}$	-	7	15	-	19	-	22	ns
		$V_{CC} = 6.0\text{ V}$	-	6	13	-	16	-	19	ns
		Parallel data outputs								
		$V_{CC} = 2.0\text{ V}$	-	14	60	-	75	-	90	ns
		$V_{CC} = 4.5\text{ V}$	-	5	12	-	15	-	18	ns
		$V_{CC} = 6.0\text{ V}$	-	4	10	-	13	-	15	ns

Table 8. Dynamic characteristics type 74HC594 ...continuedGND = 0 V; $t_r = t_f = 6$ ns; $C_L = 50$ pF; see [Figure 15](#).

Symbol	Parameter	Conditions	25 °C			–40 °C to +85 °C		–40 °C to +125 °C		Unit
			Min	Typ	Max	Min	Max	Min	Max	
t_{TLH}	LOW to HIGH output transition time	see Figure 9								
		Serial data output Q7S								
		$V_{CC} = 2.0$ V	-	19	75	-	95	-	110	ns
		$V_{CC} = 4.5$ V	-	7	15	-	19	-	22	ns
		$V_{CC} = 6.0$ V	-	6	13	-	16	-	19	ns
		Parallel data outputs								
		$V_{CC} = 2.0$ V	-	14	60	-	75	-	90	ns
		$V_{CC} = 4.5$ V	-	5	12	-	15	-	18	ns
		$V_{CC} = 6.0$ V	-	4	10	-	13	-	15	ns
t_W	pulse width	SHCP (HIGH or LOW); see Figure 9								
		$V_{CC} = 2.0$ V	80	10	-	100	-	120	-	ns
		$V_{CC} = 4.5$ V	16	4	-	20	-	24	-	ns
		$V_{CC} = 6.0$ V	14	3	-	17	-	20	-	ns
		STCP (HIGH or LOW); see Figure 10								
		$V_{CC} = 2.0$ V	80	10	-	100	-	120	-	ns
		$V_{CC} = 4.5$ V	16	4	-	20	-	24	-	ns
		$V_{CC} = 6.0$ V	14	3	-	17	-	20	-	ns
		SHR and STR (HIGH or LOW); see Figure 13 and Figure 14								
		$V_{CC} = 2.0$ V	80	14	-	100	-	120	-	ns
		$V_{CC} = 4.5$ V	16	5	-	20	-	24	-	ns
		$V_{CC} = 6.0$ V	14	4	-	17	-	20	-	ns

Table 8. Dynamic characteristics type 74HC594 ...continuedGND = 0 V; $t_r = t_f = 6$ ns; $C_L = 50$ pF; see [Figure 15](#).

Symbol	Parameter	Conditions	25 °C			–40 °C to +85 °C		–40 °C to +125 °C		Unit
			Min	Typ	Max	Min	Max	Min	Max	
t _{su}	set-up time	DS to SHCP; see Figure 11								
		V _{CC} = 2.0 V	100	10	-	125	-	150	-	ns
		V _{CC} = 4.5 V	20	4	-	25	-	30	-	ns
		V _{CC} = 6.0 V	17	3	-	21	-	26	-	ns
		SHR to STCP; see Figure 12								
		V _{CC} = 2.0 V	100	14	-	125	-	150	-	ns
		V _{CC} = 4.5 V	20	5	-	25	-	30	-	ns
		V _{CC} = 6.0 V	17	4	-	21	-	26	-	ns
		SHCP to STCP; see Figure 10								
		V _{CC} = 2.0 V	100	17	-	125	-	150	-	ns
		V _{CC} = 4.5 V	20	6	-	25	-	30	-	ns
		V _{CC} = 6.0 V	17	5	-	21	-	26	-	ns
t _h	hold time	DS to SHCP; see Figure 11								
		V _{CC} = 2.0 V	25	–8	-	30	-	35	-	ns
		V _{CC} = 4.5 V	5	–3	-	6	-	7	-	ns
		V _{CC} = 6.0 V	4	–2	-	5	-	6	-	ns
t _{rec}	recovery time	SHR to SHCP and STR to STCP; see Figure 13 and Figure 14								
		V _{CC} = 2.0 V	50	–14	-	65	-	75	-	ns
		V _{CC} = 4.5 V	10	–5	-	13	-	15	-	ns
		V _{CC} = 6.0 V	9	–4	-	11	-	13	-	ns
f _{max}	maximum frequency	SHCP or STCP; see Figure 9 and Figure 10								
		V _{CC} = 2.0 V	6.0	30	-	4.8	-	4.0	-	MHz
		V _{CC} = 4.5 V	30	92	-	24	-	20	-	MHz
		V _{CC} = 5.0 V; C _L = 15 pF	-	100	-	-	-	-	-	MHz
		V _{CC} = 6.0 V	35	109	-	28	-	24	-	MHz

Table 8. Dynamic characteristics type 74HC594 ...continuedGND = 0 V; $t_r = t_f = 6$ ns; $C_L = 50$ pF; see [Figure 15](#).

Symbol	Parameter	Conditions	25 °C			–40 °C to +85 °C		–40 °C to +125 °C		Unit
			Min	Typ	Max	Min	Max	Min	Max	
C_{PD}	power dissipation capacitance	$V_I = \text{GND to } V_{CC}$; [2] $V_{CC} = 5$ V; $f_i = 1$ MHz	-	84	-	-	-	-	-	pF

[1] t_{pd} is the same as t_{PHL} and t_{PLH} .[2] C_{PD} is used to determine the dynamic power dissipation (P_D in μW): $P_D = C_{PD} \times V_{CC}^2 \times f_i \times N + \Sigma(C_L \times V_{CC}^2 \times f_o)$ where: f_i = input frequency in MHz; f_o = output frequency in MHz; C_L = output load capacitance in pF; V_{CC} = supply voltage in V; N = number of inputs switching; $\Sigma(C_L \times V_{CC}^2 \times f_o)$ = sum of outputs.**Table 9.** Dynamic characteristics type 74HCT594GND = 0 V; $V_{CC} = 4.5$ V; $t_r = t_f = 6$ ns; $C_L = 50$ pF; see [Figure 15](#).

Symbol	Parameter	Conditions	25 °C			–40 °C to +85 °C		–40 °C to +125 °C		Unit
			Min	Typ	Max	Min	Max	Min	Max	
t_{pd}	propagation delay	SHCP to Q7S; see Figure 9	-	18	32	-	40	-	48	ns
		$V_{CC} = 5.0$ V; $C_L = 15$ pF	-	15	-	-	-	-	-	ns
		STCP to Qn; see Figure 10	-	18	32	-	40	-	48	ns
		$V_{CC} = 5.0$ V; $C_L = 15$ pF	-	15	-	-	-	-	-	ns
t_{PHL}	HIGH to LOW propagation delay	SHR to Q7S; see Figure 13	-	17	30	-	38	-	45	ns
		$V_{CC} = 5.0$ V; $C_L = 15$ pF	-	14	-	-	-	-	-	ns
		STR to Qn; see Figure 14	-	17	30	-	38	-	45	ns
		$V_{CC} = 5.0$ V; $C_L = 15$ pF	-	14	-	-	-	-	-	ns
t_{THL}	HIGH to LOW output transition time	see Figure 9								
		Serial data output Q7S								
		$V_{CC} = 4.5$ V	-	7	15	-	19	-	22	ns
t_{TLH}	LOW to HIGH output transition time	Parallel data outputs								
		$V_{CC} = 4.5$ V	-	5	12	-	15	-	18	ns
		Serial data output Q7S								
t_{TLH}	LOW to HIGH output transition time	$V_{CC} = 4.5$ V	-	7	15	-	19	-	22	ns
		Parallel data outputs								
		$V_{CC} = 4.5$ V	-	5	12	-	15	-	18	ns

Table 9. Dynamic characteristics type 74HCT594 ...continuedGND = 0 V; V_{CC} = 4.5 V; t_r = t_f = 6 ns; C_L = 50 pF; see [Figure 15](#).

Symbol	Parameter	Conditions	25 °C			–40 °C to +85 °C		–40 °C to +125 °C		Unit
			Min	Typ	Max	Min	Max	Min	Max	
t _W	pulse width	SHCP (HIGH or LOW); see Figure 9	16	4	-	20	-	24	-	ns
		STCP (HIGH or LOW); see Figure 10	16	4	-	20	-	24	-	ns
		SHR and STR (HIGH or LOW); see Figure 13 and Figure 14	16	6	-	20	-	24	-	ns
t _{su}	set-up time	DS to SHCP; see Figure 11	20	4	-	25	-	30	-	ns
		SHR to STCP; see Figure 12	20	6	-	25	-	30	-	ns
		SHCP to STCP; see Figure 10	20	7	-	25	-	30	-	ns
t _h	hold time	DS to SHCP; see Figure 11	5	–3	-	6	-	7	-	ns
t _{rec}	recovery time	SHR to SHCP and STR to STCP; see Figure 13 and Figure 14	10	–5	-	13	-	15	-	ns
f _{max}	maximum frequency	SHCP or STCP; see Figure 9 and Figure 10	30	92	-	24	-	20	-	MHz
		V _{CC} = 5.0 V; C _L = 15 pF	-	100	-	-	-	-	-	MHz
C _{PD}	power dissipation capacitance	V _I = GND to V _{CC} – 1.5 V; V _{CC} = 5 V; f _i = 1 MHz	-	89	-	-	-	-	-	pF

[1] t_{pd} is the same as t_{PHL} and t_{PLH}.[2] C_{PD} is used to determine the dynamic power dissipation (P_D in μW):

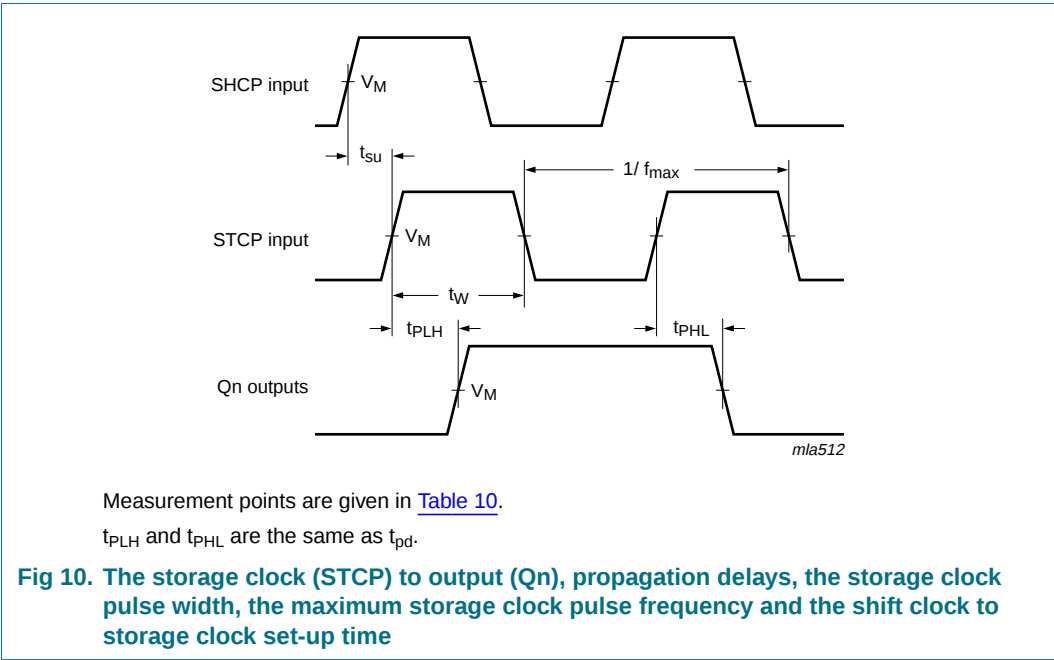
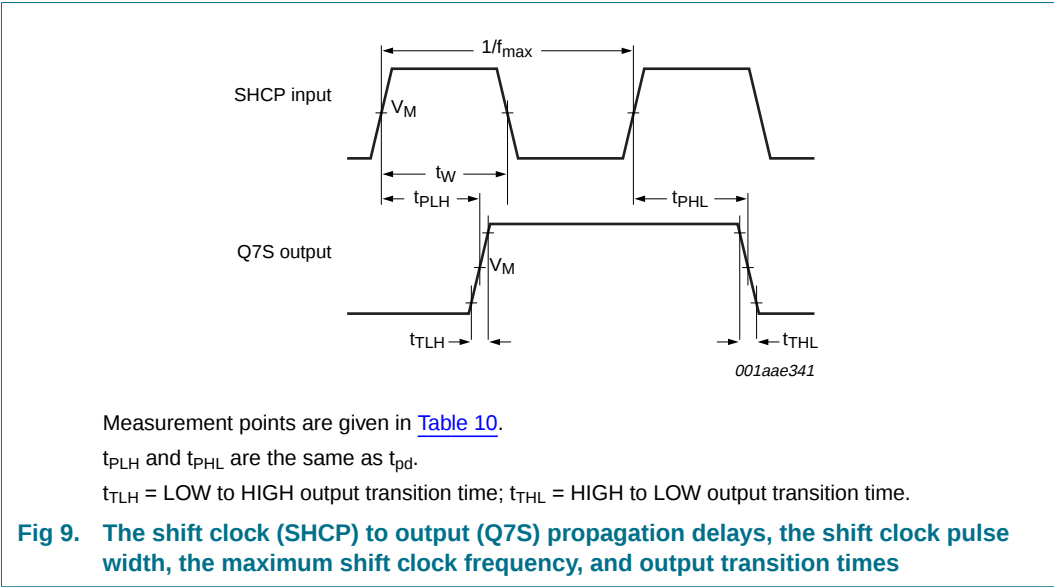
$$P_D = C_{PD} \times V_{CC}^2 \times f_i \times N + \sum (C_L \times V_{CC}^2 \times f_o) \text{ where:}$$

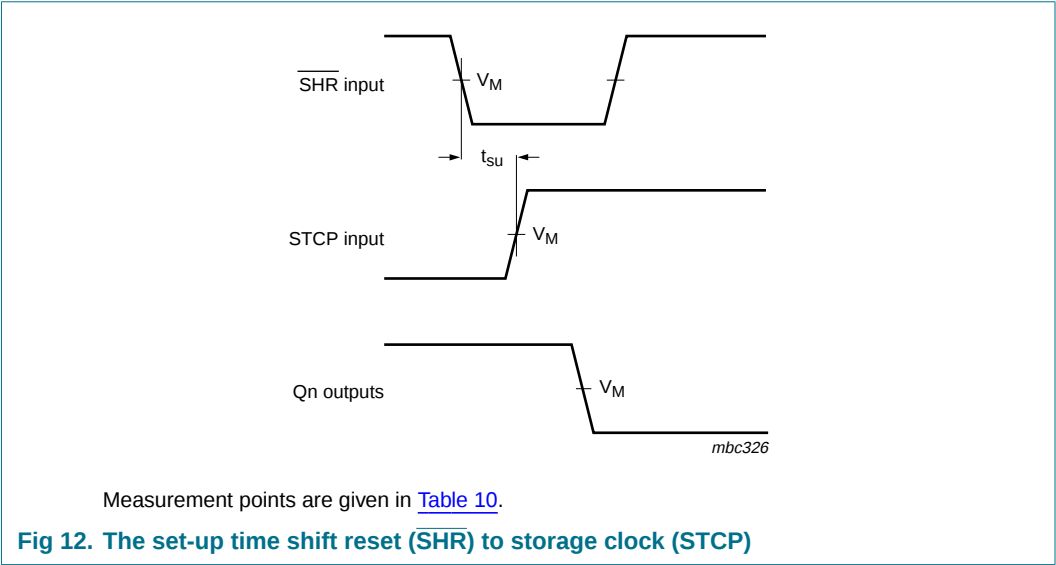
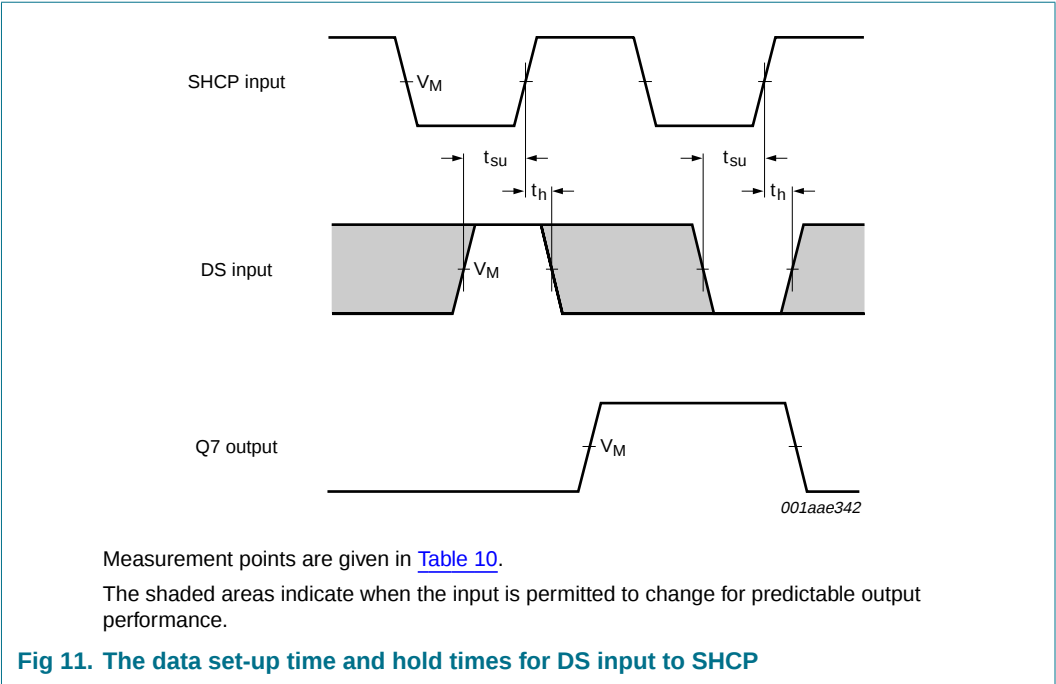
f_i = input frequency in MHz;f_o = output frequency in MHz;C_L = output load capacitance in pF;V_{CC} = supply voltage in V;

N = number of inputs switching;

 $\sum (C_L \times V_{CC}^2 \times f_o)$ = sum of outputs.

12. Waveforms





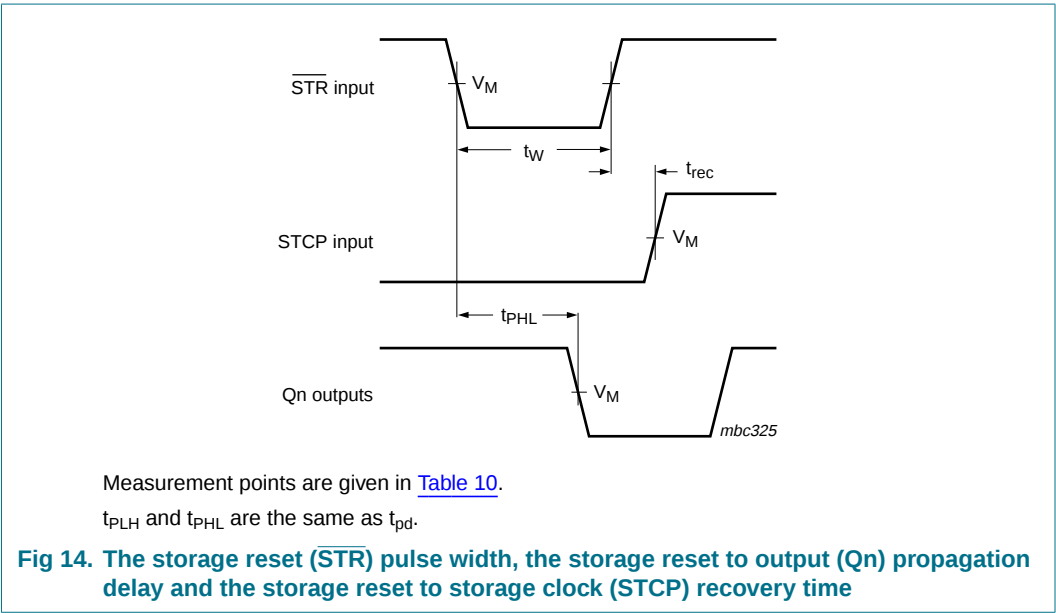
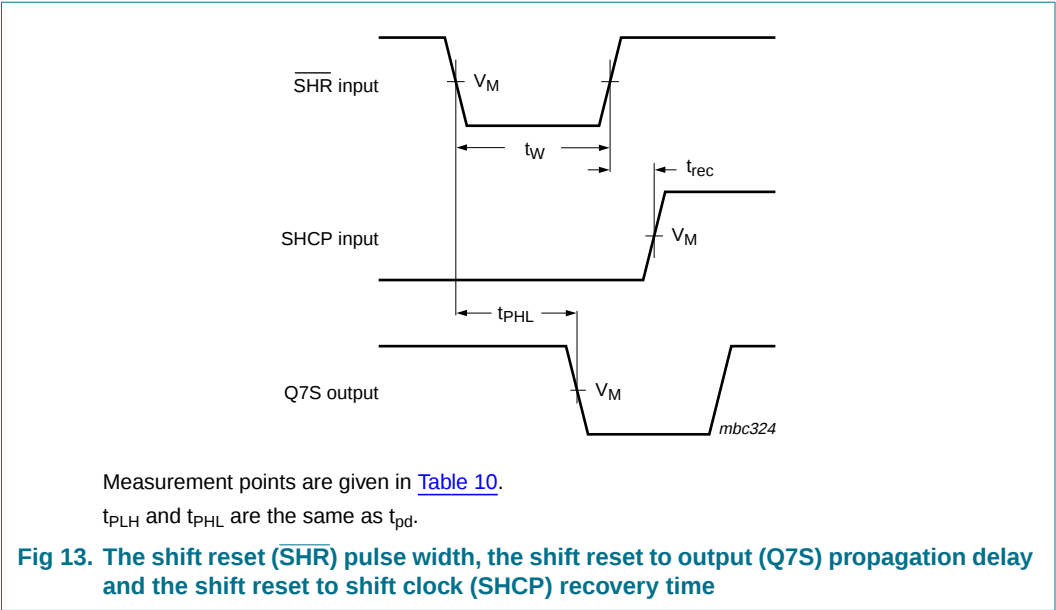


Table 10. Measurement points

Type	Input	Output
	V_M	V_M
74HC594	$0.5 \times V_{CC}$	$0.5 \times V_{CC}$
74HCT594	1.3 V	1.3 V

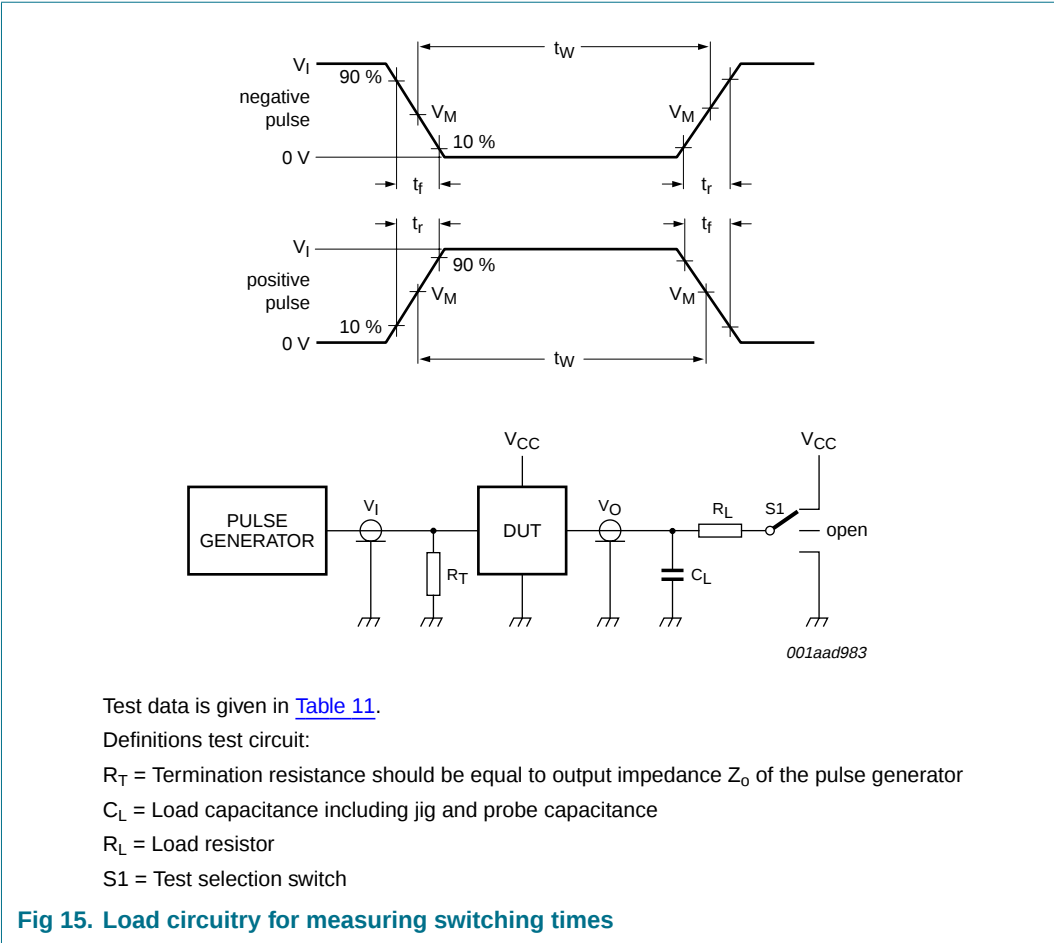


Fig 15. Load circuitry for measuring switching times

Table 11. Test data

Type	Input		Load		S1 position		
	V_I	t_r, t_f	C_L	R_L	t_{PHL}, t_{PLH}	t_{PZH}, t_{PHZ}	t_{PZL}, t_{PLZ}
74HC594	V_{CC}	6 ns	15 pF, 50 pF	1 k Ω	open	GND	V_{CC}
74HCT594	3 V	6 ns	15 pF, 50 pF	1 k Ω	open	GND	V_{CC}

13. Package outline

SO16: plastic small outline package; 16 leads; body width 3.9 mm

SOT109-1

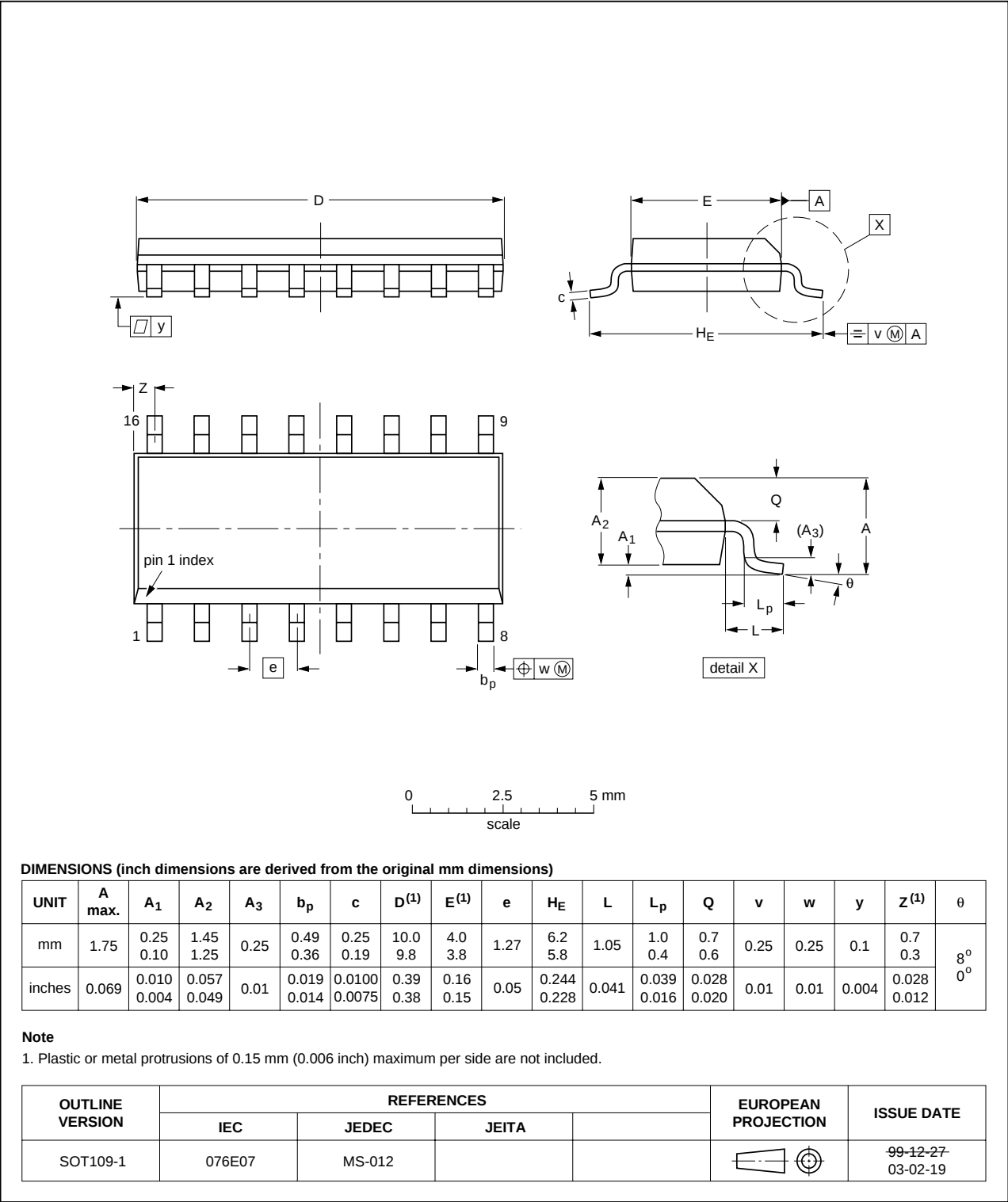


Fig 16. Package outline SOT109-1 (SO16)

SSOP16: plastic shrink small outline package; 16 leads; body width 5.3 mm

SOT338-1

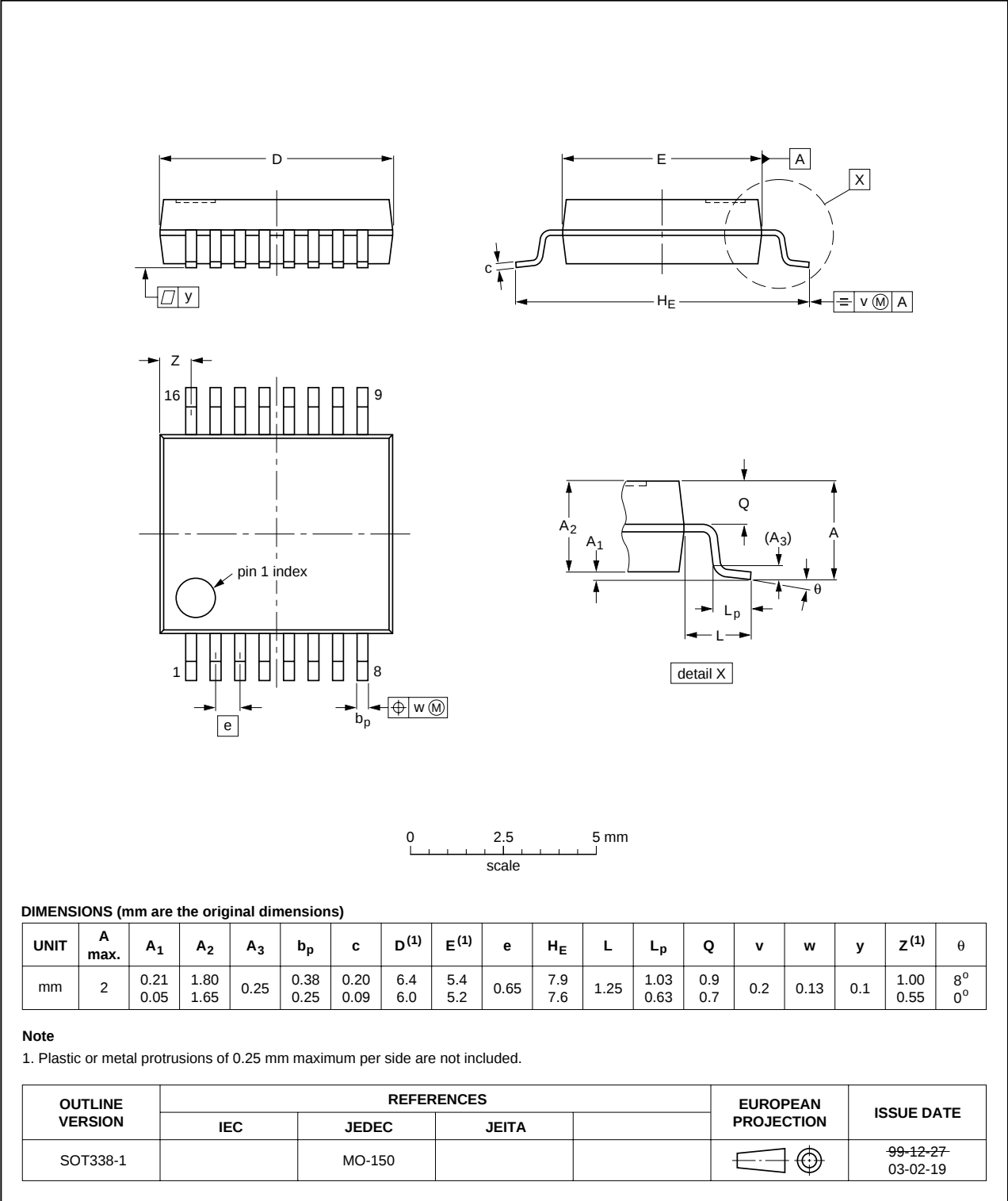


Fig 17. Package outline SOT338-1 (SSOP16)

DIP16: plastic dual in-line package; 16 leads (300 mil)

SOT38-4

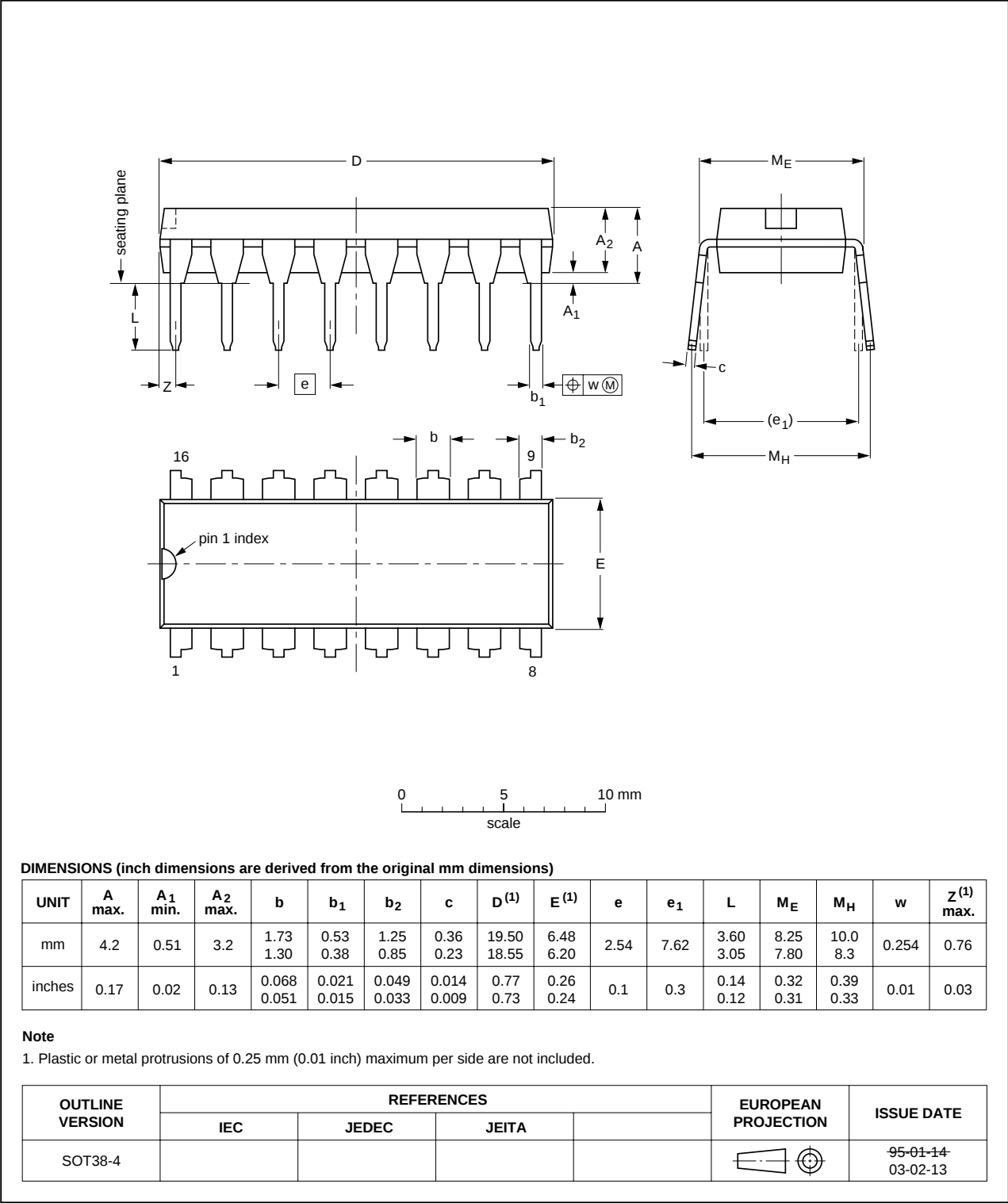


Fig 18. Package outline SOT38-4 (DIP16)

14. Abbreviations

Table 12. Abbreviations

Acronym	Description
CMOS	Complementary Metal Oxide Semiconductor
DUT	Device Under Test
ESD	ElectroStatic Discharge
HBM	Human Body Model
LSTTL	Low-Power Schottky Transistor-Transistor Logic
MM	Machine Model
TTL	Transistor-Transistor Logic

15. Revision history

Table 13. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
74HC_HCT594_3	20061220	Product data sheet	-	74HC_HCT594_CNV_2
Modifications:	• The format of this data sheet has been redesigned to comply with the new identity guidelines of NXP Semiconductors. • Legal texts have been adapted to the new company name where appropriate. • Table 1 "Ordering information" updated.			
74HC_HCT594_CNV_2	19970908	Product specification	-	74HC_HCT594_CNV_1

16. Legal information

16.1 Data sheet status

Document status ^{[1][2]}	Product status ^[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

[3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL <http://www.nxp.com>.

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